Wire bonder *“WESTBOND 7476E”*

- **Location: Fab3**
- **Manufacurer site**

http://www.westbond.com/index.htm

http://www.westbond.com/7476E.htm

http://www.westbond.com/7400espc.htm

- **Representative**

http://g-electronics.co.il/contact_us.html

- ***User manual***

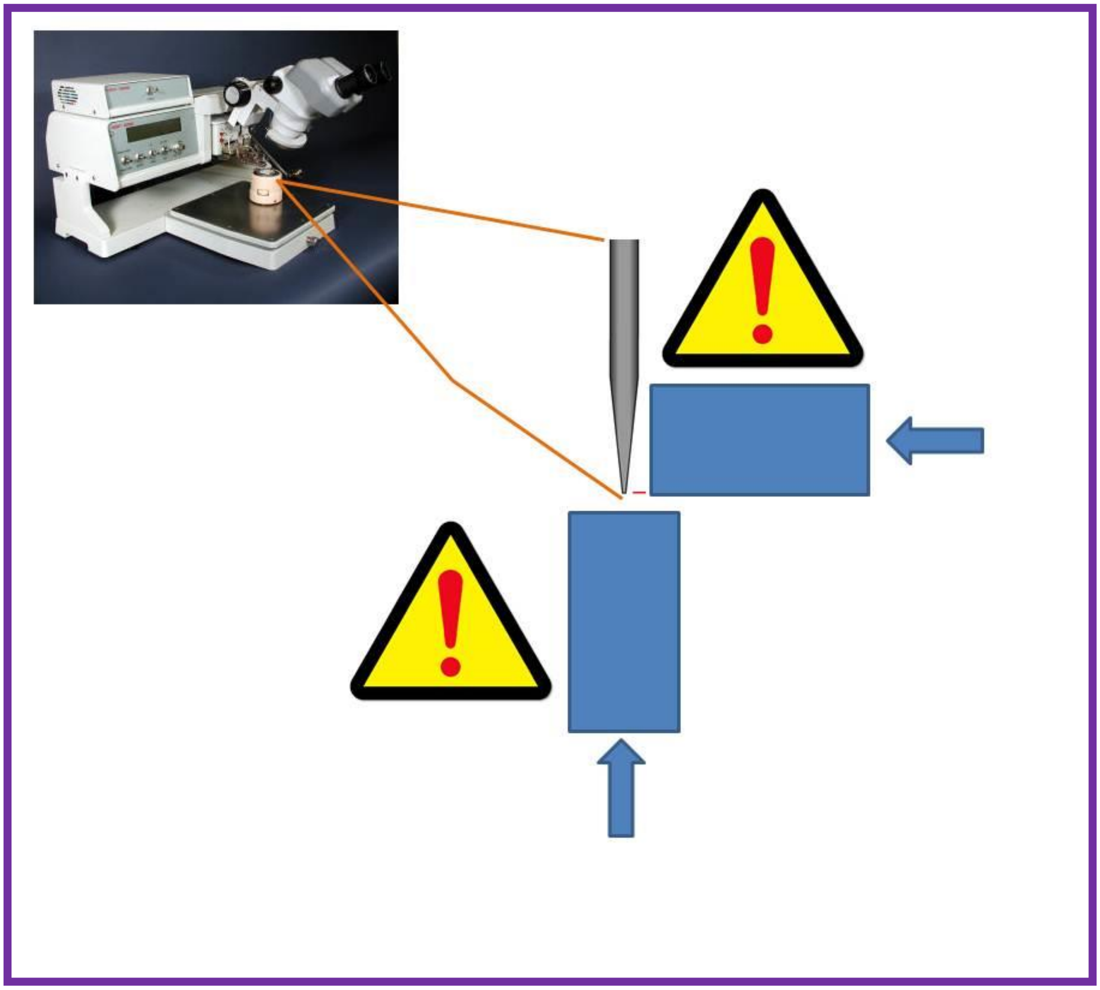
Read carefully use manual before working on the machine GO

- **Check before work GO**

- **Programing GO**

- **Caution !!**

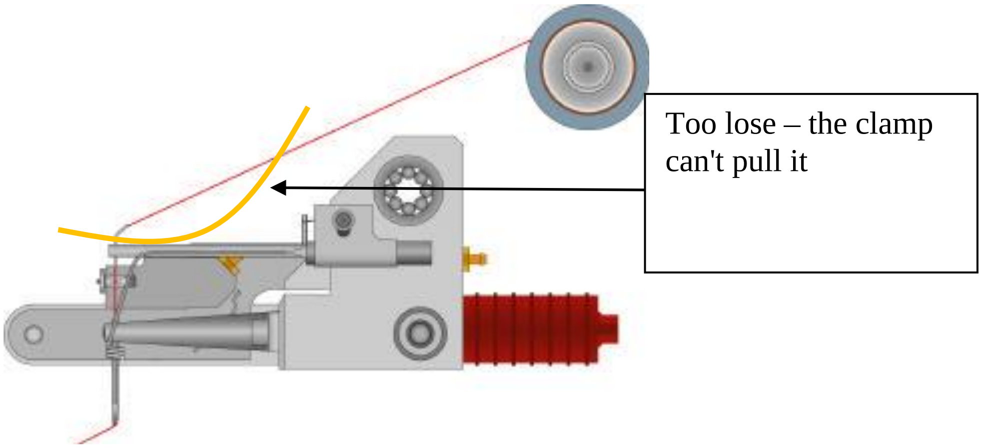
Be careful not to harm the wedge edge!!



Check before work

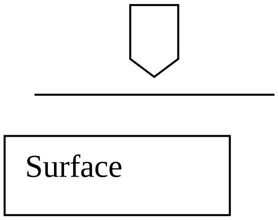
1. Air pressure.

   50PSI. verify the valve at the wall is open.
2. Buffer (parameters).
3. Temperature.
4. Distance from wedge to surface.
5. Compatibility of wire – wedge – surface.
6. Wire doesn’t too tense or too loose



Too lose – the clamp can't pull it

7. **Flatness! The surface must be 90 degrees to the wedge.**
8. **The large x-y stage should be on top!**



Programs

The menu is:

Feed / Open Prev / Next	Buffer	Edit /Esc. US	Up /Down	

Open: open the clamp. In Edit mode it moves Prev / Next.

Buffer – Next / Previous buffer.

Edit: keeping on pressing Edit brings you to the parameters. Esc. – out of Edit.

Up /Down: changes the parameters of Edit.

Program parameters change according to the surfaces (wire, and / or surface).

The bonder works with metallic surfaces! These surfaces are relatively soft, so hard materials as Si can't be bonded!

- **Microscope:** Nikon SMZ660 (not "Olympus SZ3060ESD" as mentioned in the user manual).

http://www.nikon.com/products/instruments/lineup/industrial/stereoscopic_microscopes/smz660/index.htm